

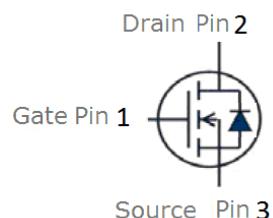
Features

- N-Channel, 10V Logic Level Control
- Enhancement mode
- Low on-resistance $R_{DS(on)}$ @ $V_{GS}=10$ V
- Fast Switching
- Pb-free lead plating; RoHS compliant


Halogen-Free

Part ID	Package Type	Marking	Tape and reel information
VS4N60AI	TO-251SL	4N60AI	75pcs/Tube

V_{DS}	600	V
$R_{DS(on),TYP}$ @ $V_{GS}=10$ V	2.9	Ω
I_D	4	A

TO-251SL


Maximum ratings, at $T_A = 25^\circ\text{C}$, unless otherwise specified

Symbol	Parameter	Rating	Unit
$V_{(BR)DSS}$	Drain-Source breakdown voltage	600	V
V_{GS}	Gate-Source voltage	± 30	V
I_s	Diode continuous forward current	$T_C = 25^\circ\text{C}$	A
I_D	Continuous drain current @ $V_{GS}=10$ V	$T_C = 25^\circ\text{C}$	A
		$T_C = 100^\circ\text{C}$	2.5
I_{DM}	Pulse drain current tested ①	$T_C = 25^\circ\text{C}$	A
I_{DSM}	Continuous drain current @ $V_{GS}=10$ V	$T_A = 25^\circ\text{C}$	A
		$T_A = 70^\circ\text{C}$	0.4
EAS	Avalanche energy, single pulsed ②	26	mJ
P_D	Maximum power dissipation	$T_C = 25^\circ\text{C}$	W
P_{DSM}	Maximum power dissipation ③	$T_A = 25^\circ\text{C}$	W
T_{STG}, T_J	Storage and Junction Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typical	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	2	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	100	°C/W

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Static Electrical Characteristics @ $T_j=25^\circ\text{C}$ (unless otherwise stated)						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	600	668	--	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=600\text{V}, V_{\text{GS}}=0\text{V}$	--	--	1	μA
	Zero Gate Voltage Drain Current($T_j=125^\circ\text{C}$)	$V_{\text{DS}}=480\text{V}, V_{\text{GS}}=0\text{V}$	--	--	50	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 30\text{V}, V_{\text{DS}}=0\text{V}$	--	--	± 100	nA
$V_{\text{GS}(\text{TH})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	2.4	3	3.6	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance ④	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=2\text{A}$	--	2.9	3.6	Ω
Dynamic Electrical Characteristics @ $T_j = 25^\circ\text{C}$ (unless otherwise stated)						
C_{iss}	Input Capacitance	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	300	380	460	pF
C_{oss}	Output Capacitance		25	40	55	pF
C_{rss}	Reverse Transfer Capacitance		--	6	10	pF
R_g	Gate Resistance	f=1MHz	--	6.9	--	Ω
Q_g	Total Gate Charge	$V_{\text{DS}}=480\text{V}, I_{\text{D}}=4\text{A}, V_{\text{GS}}=10\text{V}$	--	13	--	nC
Q_{gs}	Gate-Source Charge		--	4.7	--	nC
Q_{qd}	Gate-Drain Charge		--	5.8	--	nC
Switching Characteristics						
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=300\text{V}, I_{\text{D}}=4\text{A}, R_{\text{G}}=25\Omega, V_{\text{GS}}=10\text{V}$	--	20	--	ns
t_r	Turn-on Rise Time		--	35	--	ns
$t_{\text{d(off)}}$	Turn-Off Delay Time		--	33	--	ns
t_f	Turn-Off Fall Time		--	28	--	ns
Source- Drain Diode Characteristics@ $T_j = 25^\circ\text{C}$ (unless otherwise stated)						
V_{SD}	Forward on voltage	$I_{\text{SD}}=4\text{A}, V_{\text{GS}}=0\text{V}$	--	0.9	1.2	V
t_{rr}	Reverse Recovery Time	$T_j=25^\circ\text{C}, I_{\text{sd}}=4\text{A}, V_{\text{GS}}=0\text{V}$ $dI/dt=100\text{A}/\mu\text{s}$	--	89	--	ns
Q_{rr}	Reverse Recovery Charge		--	0.2	--	μC

NOTE:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Limited by $T_{j\text{max}}$, starting $T_j = 25^\circ\text{C}$, $L = 1\text{mH}$, $R_G = 25\Omega$, $I_{AS} = 7\text{A}$, $V_{GS} = 10\text{V}$. Part not recommended for use above this value
- ③ The power dissipation P_{DSM} is based on $R_{\theta JA}$ and the maximum allowed junction temperature of 150°C .
- ④ Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.



Vanguard
Semiconductor

VS4N60AI

600V/4A N-Channel Advanced Power MOSFET

Typical Characteristics

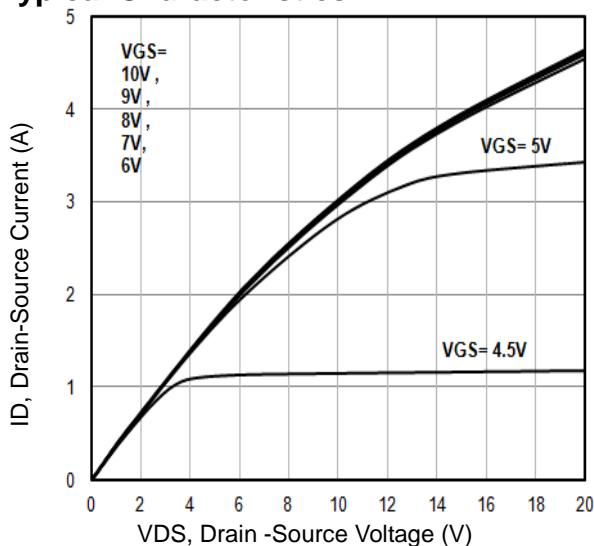


Fig1. Typical Output Characteristics

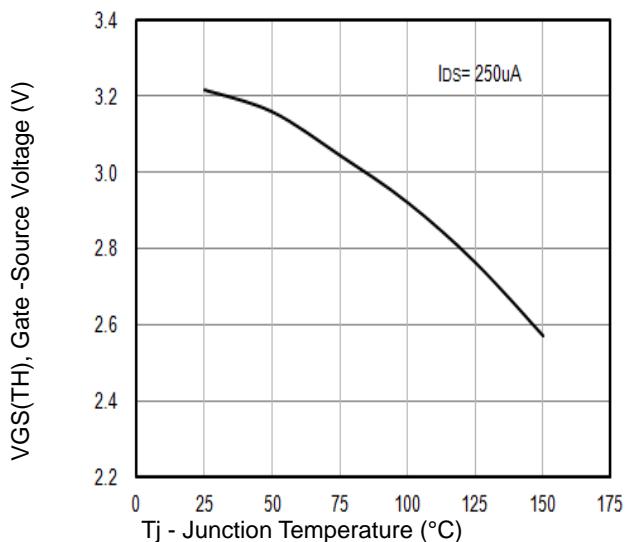


Fig2. $V_{GS(TH)}$ Gate -Source Voltage Vs. T_j

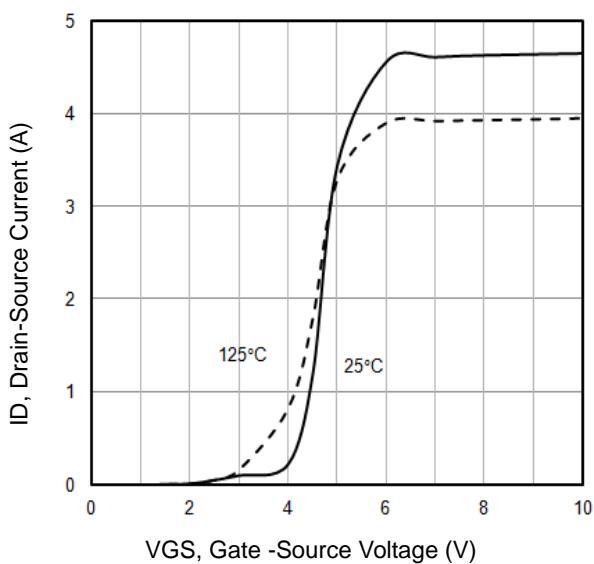


Fig3. Typical Transfer Characteristics

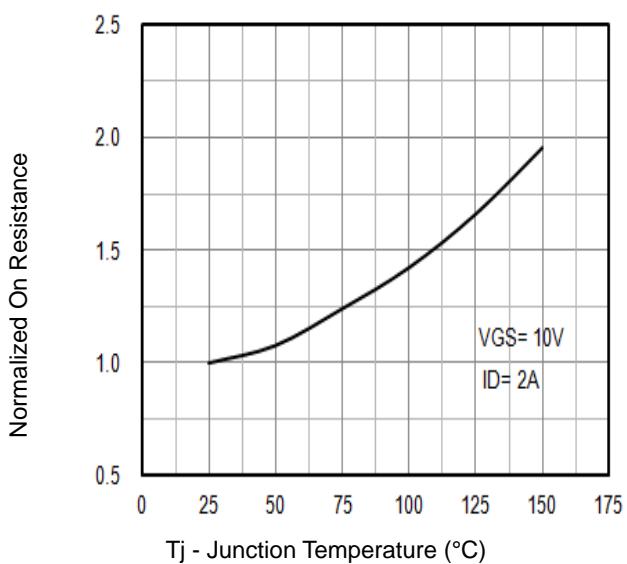


Fig4. Normalized On-Resistance Vs. T_j

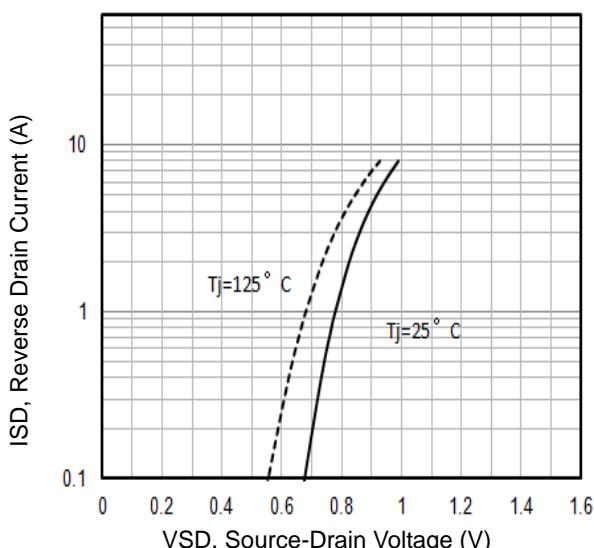


Fig5. Typical Source-Drain Diode Forward Voltage

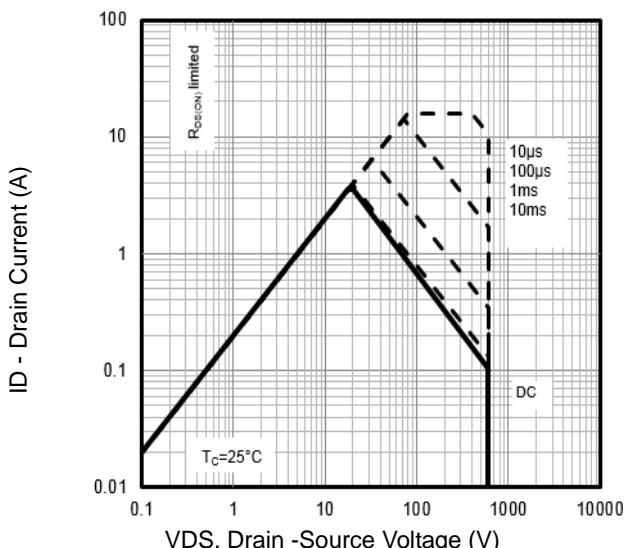


Fig6. Maximum Safe Operating Area



Typical Characteristics

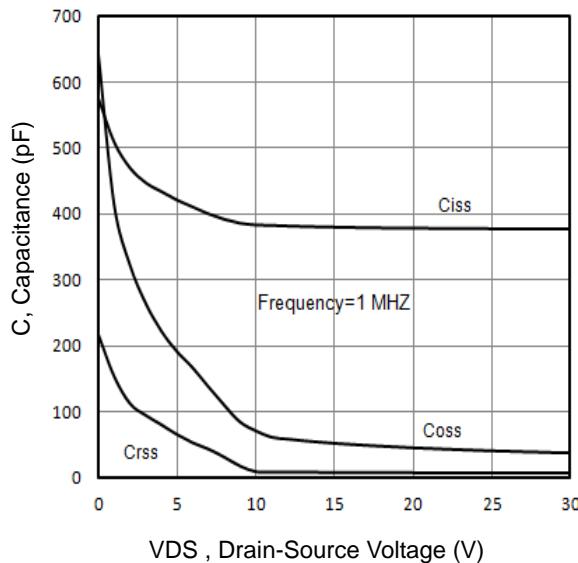


Fig7. Typical Capacitance Vs.Drain-Source Voltage

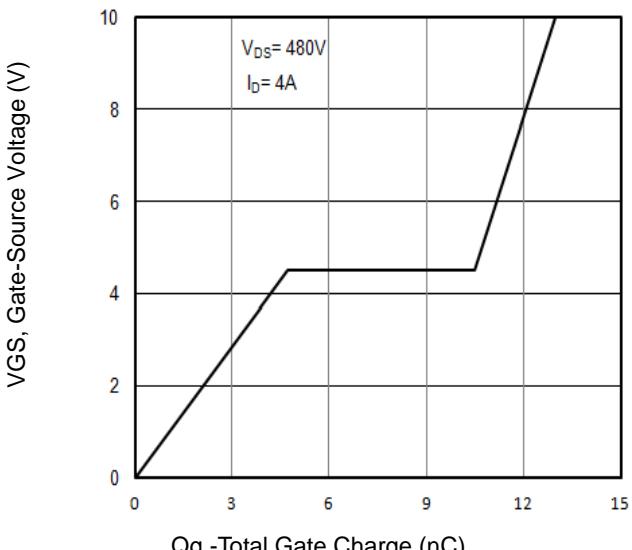


Fig8. Typical Gate Charge Vs.Gate-Source Voltage

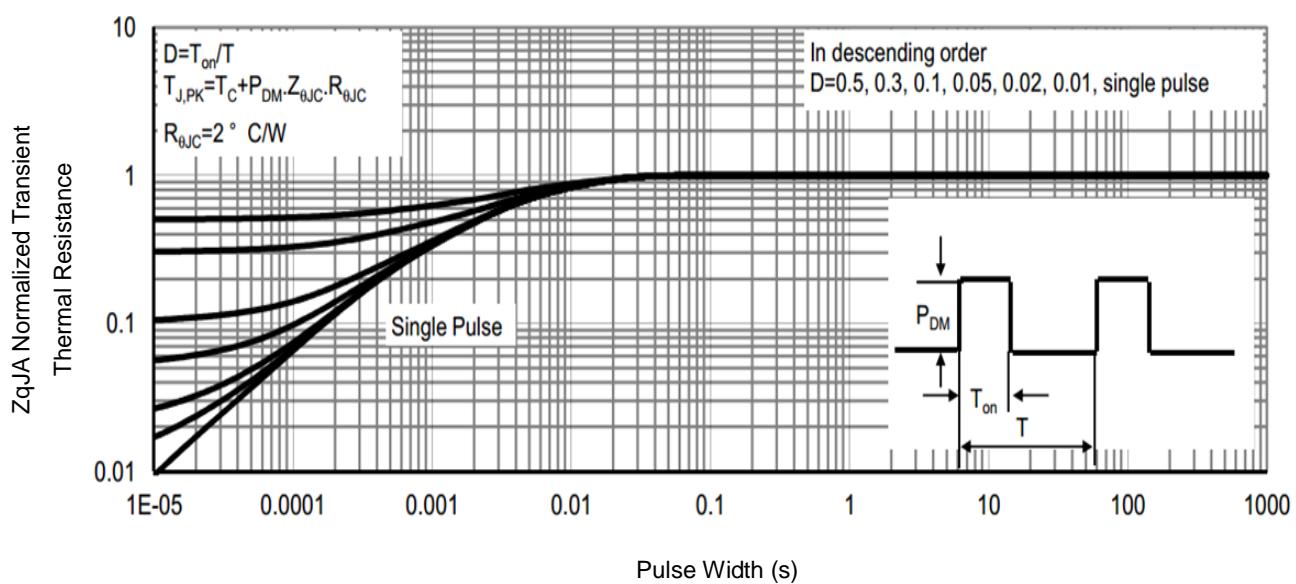


Fig9. Normalized Maximum Transient Thermal Impedance

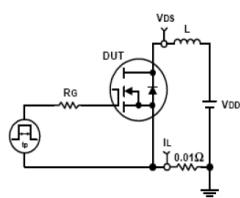


Fig10. Unclamped Inductive Test Circuit and waveforms

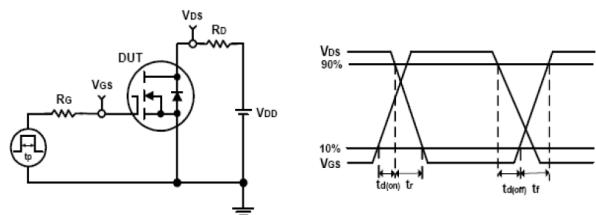
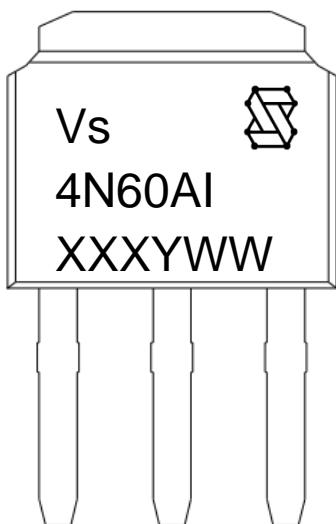


Fig11. Switching Time Test Circuit and waveforms

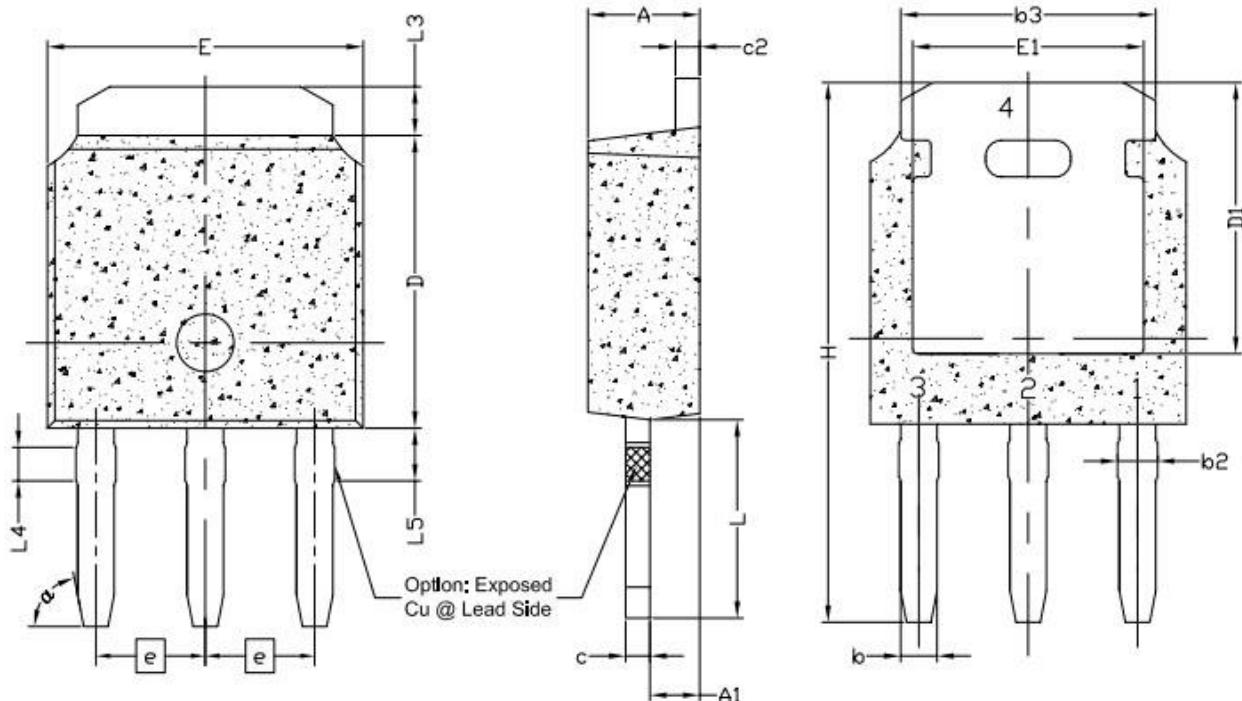
Marking Information



- 1st line: Vanguard Code (Vs), Vanguard Logo
2nd line: Part Number (4N60AI)
3rd line: Date code (XXXYWW)
 XXX: Wafer Lot Number
 Y: Year Code, e.g. E means 2017
 WW: Week Code



TO-251SL Package Outline Data



Symbol	Dimensions (unit: mm)		
	Min	Typ	Max
A	2.20	2.30	2.39
A1	0.89	1.04	1.15
b	0.64	0.76	0.89
b2	0.77	0.84	1.14
b3	5.21	5.34	5.46
c	0.46	0.50	0.60
c2	0.46	0.50	0.60
D	5.98	6.10	6.223
D1	5.10	--	--
E	6.40	6.60	6.731
E1	4.40	--	--
e	2.286 BSC		
H	11.05	11.25	11.45
L	3.98	4.13	4.35
L3	0.89	--	1.27
L4	0.698 REF		
L5	0.972	1.099	1.226
α	79° REF		

Notes:

- Dimension "D" and "E" do NOT include mold flash, protrusion or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 0.1mm per side.

Customer Service

Sales and Service:

sales@vgsemi.com

Vanguard Semiconductor CO., LTD

TEL: (86-755) -26902410

FAX: (86-755) -26907027

WEB: www.vgsemi.com